

International Conference and Exhibition
on
Device Packaging

www.imaps.org/devicepackaging

Radisson Fort McDowell Resort & Casino
Scottsdale/Fountain Hills, Arizona - USA
March 8 - 11, 2010



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IMAPS

International Microelectronics And Packaging Society
Bringing Together the Entire Microelectronics Supply Chain!

**Abstract Deadline Extended:
December 14, 2009**

Announcement and Call for Abstracts

**Topical Workshop on
Wafer Level Packaging**

This workshop is being held as a part of the Device Packaging Conference

Technical Chairs:

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Wafer Level Packaging Organizing Committee:

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Wafer Level Packaging Workshop Focus: The objective of the Wafer Level Chip Scale Packaging Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of Wafer Level Packaging. This workshop has been specifically organized to allow for the presentation and debate of some of the latest and hottest technologies out there related to these new packaging technologies. **Abstracts are being requested on the following topics:**

- Redistribution and Repassivation
- Under Bump Metallization
- WLSCP Solder Bumping
- Wafer Thining
- Backside Coating
- Laser Marking
- Dicing
- Testing and Modeling
- Mechanical
- Thermal
- Electrical
- Applications

The Wafer Level Chip Scale Packaging Workshop will also be organizing an evening Panel Session on "Industry Directions in WLCSP", in conjunction with the WLCSP Forum (www.wlcspforum.org).

Those wishing to present in the Wafer Level Packaging sector of the Device Packaging Conference must submit a 200-300 word abstract electronically **no later than December 14, 2009**, using the on-line submittal form at: www.imaps.org/abstracts.htm. No formal technical paper is required. A reproduction-ready two to six page concise summary with text (figures and graphs included if necessary) will be required for the abstract booklet on Friday, January 29, 2010. A post-conference CD containing the full presentation material as supplied by authors will be mailed 15 business days after the event to all attendees. Please contact Jackki Morris-Joyner by email at jmorris@imaps.org or by phone at 305-382-8433 if you have questions.

In addition, this year, the track Technical Chairs will be choosing select papers from the Conference for inclusion in a volume entitled "Advanced Microelectronic Packaging 2009". Participation is not mandatory, but we're sure many of you will want to participate in this highly exciting new concept. Papers not selected for this volume will, as always, have submission to the IMAPS online journal and submission to the annual IMAPS fall meeting as future options.

Device Packaging Exhibit and Technology Show: IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of Wafer Level Chip Scale Packaging. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before February 4, 2010 at: www.imaps.org/devicepackaging or contact Ann Bell by email at abell@imaps.org or by phone at 202-548-8717.

Device Packaging Professional Development Courses (PDCs): For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 8th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course to Jackki Morris-Joyner by email at jmorris@imaps.org **no later than December 14, 2009.**